

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N10S4L-35	**Issued**	24. February 2022
MA#	MA005700848		
Package	PG-TDSON-8-4	**Weight***	96.63 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.028	1.06	1.06	10633	10633
chip_2	inorganic material	silicon	7440-21-3	1.028	1.06	1.06	10633	10633
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.044	0.05		460	
	non noble metal	copper	7440-50-8	44.409	45.97	46.03	459570	460168
wire	non noble metal	aluminium	7429-90-5	0.748	0.77	0.77	7737	7737
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		936	
	plastics	epoxy resin	-	6.423	6.65		66468	
	inorganic material	silicondioxide	60676-86-0	38.719	40.07	46.81	400683	468087
leadfinish	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13532	13532
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	497	498
solder	non noble metal	tin	7440-31-5	0.051	0.05		523	
	noble metal	silver	7440-22-4	0.063	0.07		654	
	non noble metal	lead	7439-92-1	2.415	2.50	2.62	24997	26174
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2534	2538
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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